

Product Data Sheet

Flip-Chip Flux FC-WS-HT-A1

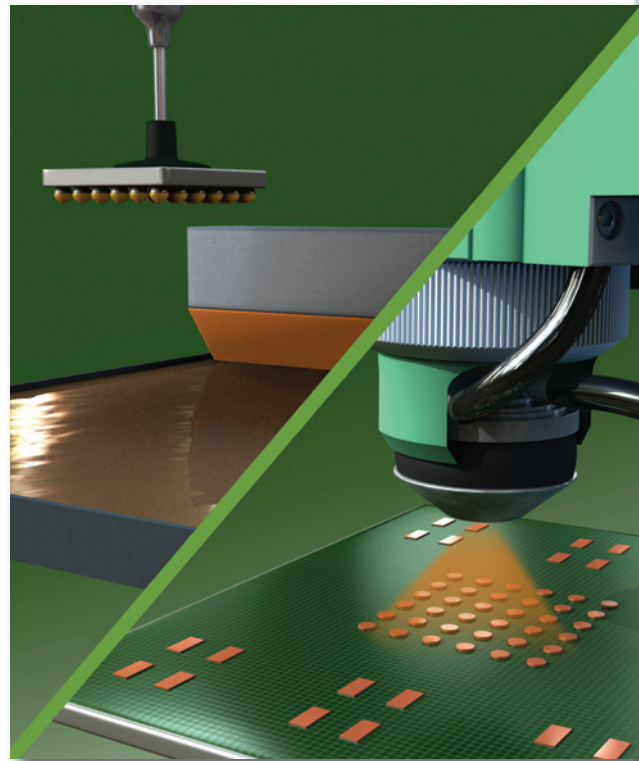
Features

- Sprayable and dispensable
- Excellent wetting ability
- Wide reflow temperature ranges

Introduction

FC-WS-HT-A1 is a water-washable, halide-free, sprayable liquid flux designed for Sn/Pb and Pb-Free wafer level solder bump formation. It can be used in a nitrogen atmosphere.

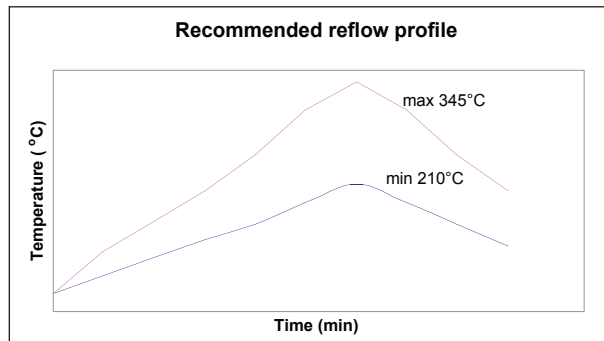
FC-WS-HT-A1 is relatively low in viscosity to accommodate spraying and spin-coating.



Properties

Typical Viscosity	5 Centistokes (cst)
Acid Number (Typical)	11
Flash point	23°C
Reflow atmosphere	Nitrogen
Max reflow temperature	345°C
SIR	Pass
Cleaning	De-Ionized (DI) Water @40psi and 55°C

Reflow



This is the standard reflow profile for FC-WS-HT-A1. The time to peak should be about 3 to 5 minutes. The peak temperature should be 20°C more than the melting point of the metal. Time above liquidus should be about 40 to 70sec.

Packaging

- 1 US gallon (3.75 liters) bottle
- 1 US pint (0.473 liter) plastic bottle
- 1 oz. (29.57 milliliters) bottle

Storage and Handling

The shelf life of **FC-WS-HT-A1** is 6 months when stored at 0–30°C.

Flux should be allowed to reach ambient working temperature prior to use. Bottles should be labeled with date and time of opening.

Material Safety Data Sheet

The MSDS for this product can be found online at <http://www.indium.com/techlibrary/msds.php>

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products

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